Application No.: 10/575,110

Reply to Office Action of: October 29, 2008

**AMENDMENTS TO THE CLAIMS** 

This listing of claims will replace all prior versions, and listings of claims in the

application:

Claim 1 (Canceled):

Claim 2 (Currently Amended): The hotmelt adhesive structure method as claimed in

claim [[1]] 17, wherein the copolyamide is an amine terminated copolyamide powder having

a melting range of 90 to 150°C and a solution viscosity eta rel in the range from 1.2 to 1.7.

Claims 3-5 (Canceled):

Claim 6 (Canceled):

Claim 7 (Currently Amended): The hotmelt adhesive structure method as claimed in

claim [[1]] 17, wherein the isocyanate has a melting range of from 100 to 130°C.

Claim 8 (Currently Amended): The hotmelt adhesive structure method as claimed in

claim [[1]] 17, wherein an epoxide having a melting range of from 90 to 130°C, a molecular

weight range from 2000 to 6000 and more than two epoxide groups per molecule is employed

as crosslinking component.

Claim 9 (Currently Amended): The hotmelt adhesive structure method as claimed in

claim [[1]] 17, wherein a pulverulent free or blocked isocyanate is employed as crosslinking

component.

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Claim 10 (Currently Amended): The hotmelt adhesive structure method as claimed in claim [[1]] 17, wherein the amine terminated copolyamides in the upper dot and lower dot have different melting temperatures or viscosities.

Claim 11 (Currently Amended): The hotmelt adhesive structure method as claimed in claim [[1]] 17, wherein the crosslinking component is an epichlorohydrin.

Claim 12 (Currently Amended): The hotmelt adhesive structure method as claimed in claim [[1]] 17, wherein the acrylic component is a di- and/or triacrylate.

Claim 13 (Currently Amended): The hotmelt adhesive structure method as claimed in claim [[1]] 17, wherein the reactive amine terminated copolyamide is employed as base dot for the double dot technology, as a strikethrough barrier.

Claim 14 (Canceled):

Claim 15 (Currently Amended): The hotmelt adhesive structure method as claimed in claim [[1]] 17, wherein the crosslinking reaction is accelerated by catalysts.

Claim 16 (Currently Amended): The hotmelt adhesive structure method as claimed in claim [[1]] 17, wherein the copolyamides are based on lactames (LL, CL), dimer fatty acids and corresponding dicarboxylic acids and diamines having chain lengths of C2 to C15 and piperazine.

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Claim 17 (Currently Amended): A method of <u>coating and/or laminating of a structure</u> in the form of a sheet, <u>comprising</u>:

contacting a -using the hotmelt adhesive structure as claimed in claim 1 for the coating and/or lamination of sheetlike with said structure structures-in the form of a sheet;

wherein said hot melt adhesive structure comprises

an upper dot and a lower dot on a substrate;

wherein the upper dot and the lower dot comprise an amine-terminated crosslinkable copolyamide and the lower dot further comprises a crosslinker and an acrylic and/or polyurethane dispersion;

wherein the crosslinker is selected from the group consisting of the isocyanates and has more than two reactive groups per molecule; and

wherein the base dot consists of a passivated isocyanate and an amine terminated copolyamide and is applied in halftone formation as a paste.

Claim 18 (Canceled):